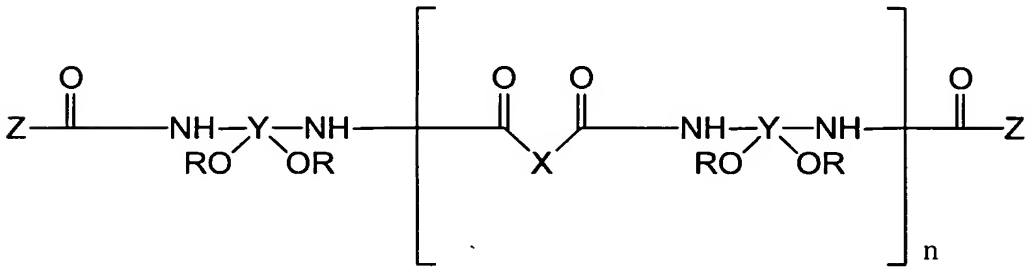
AMENDMENTS TO THE CLAIMS

This following listing of claims replaces all prior listings, and all prior versions, of claims in the application:

LISTING OF CLAIMS:

1. (Original) A photosensitive resin composition comprising:

(A) a heat-resistant polymer represented by general formula (1)



... (1)

where X represents a divalent organic group; Y represents a tetravalent organic group; Z represents a cyclic compound group free of reactive unsaturated bonds; R represents hydrogen or a monovalent organic group; and n is an integer of 2 to 500 and represents the number of repeating units of the polymer;

(B) a photoreactive compound; and

(C) a solvent.

2. (Original) The photosensitive resin composition according to claim 1, wherein at least one of the organic groups X and Y is an aromatic group.

3. (Original) The photosensitive resin composition according to claim 1, wherein

the cyclic compound group Z is a compound group having an alicyclic structure.

4. (Original) The photosensitive resin composition according to claim 2, wherein the cyclic compound group Z is a compound group having an alicyclic structure.

5. (Original) The photosensitive resin composition according to claim 3, wherein the compound group having an alicyclic structure has 3 or 4 carbon atoms.

6. (Original) The photosensitive resin composition according to claim 4, wherein the compound group having an alicyclic structure has 3 or 4 carbon atoms.

7. (Original) The photosensitive resin composition according to claim 1, wherein the divalent organic group represented by X comprises at least one divalent group derived from 3-fluoroisophthalic acid, 2-fluoroisophthalic acid, 3-fluorophthalic acid, 2-fluorophthalic acid, 2,4,5,6-tetrafluoroisophthalic acid, 3,4,5,6-tetrafluorophthalic acid, 4,4'-hexafluoroisopropylidenediphenyldicarboxylic acid, perfluorosuberic acid, 2,2'-bis(trifluoromethyl)-4,4'-biphenylenedicarboxylic acid, terephthalic acid, isophthalic acid, 4,4'-oxydiphenyldicarboxylic acid, 5-nitroisophthalic acid, 1,4-naphthalenedicarboxylic acid, 2,6-naphthalenedicarboxylic acid, and 4,4'-biphenyldicarboxylic acid.

8. (Original) The photosensitive resin composition according to claim 1, wherein the tetravalent organic group represented by Y comprises at least one divalent group

derived from 4,4'-diamino-3,3'-dihydroxybiphenyl, 2,2'-bis(3-amino-4-hydroxyphenyl)propane, and 2,2'-bis(3-amino-4-hydroxyphenyl)hexafluoropropane.

9. (Original) The photosensitive resin composition according to claim 1, wherein Z comprises at least one group selected from the group consisting of cyclopropyl, cyclobutyl, 2-phenyl-1-cyclopropyl, 1-phenyl-1-cyclopropyl, 1-benzocyclobutenyl, 2-methylcyclopropenyl, 1-hydroxy-1-cyclopropyl, 1-carboxy-1-cyclopropyl, and 1-carboxy-1-cyclobutyl.

10. (Original) The photosensitive resin composition according to claim 1, wherein the heat-resistant polymer has a weight average molecular weight in the range of 5,000 to 80,000.

11. (Original) A process for forming a relief pattern, comprising:

applying the photosensitive resin composition according to claim 1 to a support substrate and drying the composition applied to form a photosensitive resin film;

subjecting the dried photosensitive resin film to exposure;

subjecting the exposed photosensitive resin film to development using an alkaline aqueous solution; and

subjecting the developed photosensitive resin film to heating treatment.

12. (Original) An electronic component having an electronic device including at

least an interlayer dielectric film layer and a surface protecting film layer,

wherein at least one of the interlayer dielectric film layer and the surface protecting film layer comprises a resin film formed from the photosensitive resin composition according to claim 1.

13. (Currently Amended) ~~The~~ An electronic component having an electronic device including at least an interlayer dielectric film and a surface protecting layer,

wherein at least one of the interlayer dielectric film and the surface protecting layer comprises a resin film, and~~device according to claim 12~~, wherein the resin film comprises a patterned film formed by the process according to claim 11.